



Publisher Correction to: Development of SnAgCu solders with Bi and In additions and microstructural characterization of joint interface

Šimeková Beáta¹ · Hodúlová Erika¹ · Kovaříková Ingrid¹

Published online: 12 July 2018
© International Institute of Welding 2018

Publisher Correction to: Weld World (2017) 61:613–621
<https://doi.org/10.1007/s40194-017-0446-9>

In the original version of this article, the data displayed online in the “About this article” section for “Cite this article as:...,” the first and second name of the second author are incorrect. The correct citation of this article reads “Beáta, Š., Hodúlová E. and Ingrid, K. Weld World (2017) 61: 613. <https://doi.org/10.1007/s40194-017-0446-9>”.

The online version of the original article can be found at <https://doi.org/10.1007/s40194-017-0446-9>

✉ Hodúlová Erika
erika.hodulova@stuba.sk

Šimeková Beáta
beata.simekova@stuba.sk

Kovaříková Ingrid
ingrid.kovarikova@stuba.sk

¹ Materials Science and Technology in Trnava, Institute of Production, Technologies, Slovak University of Technology in Bratislava, Bratislava, Slovak Republic